ABSTRACT

MOLD FLASH REMOVAL PROCESS FOR ELECTRONIC DEVICES

A method is provided for removing excess encapsulation material from unmolded surfaces of a molded substrate including semiconductor packages by utilizing an acid solution. The method comprises the steps of mounting the substrate to a holding device with the unmolded surfaces facing an acid source for supplying an acid solution, contacting the unmolded surfaces with the acid solution for a sufficient time to remove the excess encapsulation material from the unmolded surfaces while substantially avoiding contact with molded surfaces thereof, and thereafter removing the substrate from contact with the acid solution.

(FIG. 3)